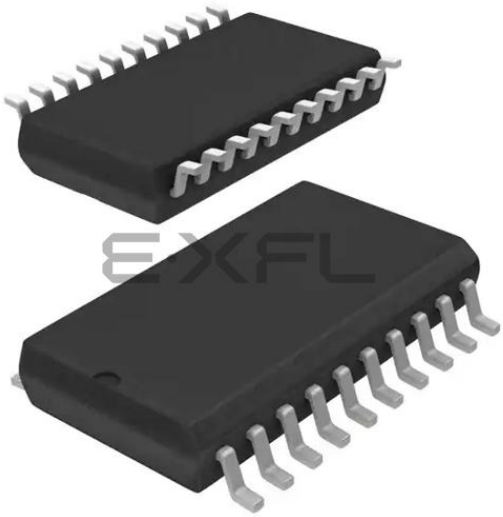

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SO
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st7flit19bf1m6

Table 2. Hardware Register Map

Address	Block	Register Label	Register Name	Reset Status	Remarks
0000h	Port A	PADR	Port A Data Register	FFh[1)]	R/W
0001h		PADDR	Port A Data Direction Register	00h	R/W
0002h		PAOR	Port A Option Register	40h	R/W
0003h	Port B	PBDR	Port B Data Register	FFh [1)]	R/W
0004h		PBDDR	Port B Data Direction Register	00h	R/W
0005h		PBOR	Port B Option Register	00h	R/W[2)]
0006h	Port C	PCDR	Port C Data Register	0xh	R/W
0007h		PCDDR	Port C Data Direction Register	00h	R/W
0008h	LITE TIMER 2	LTCSR2	Lite Timer Control/Status Register 2	00h	R/W
0009h		LTARR	Lite Timer Auto-reload Register	00h	R/W
000Ah		LTCNTR	Lite Timer Counter Register	00h	Read Only
000Bh		LTCSR1	Lite Timer Control/Status Register 1	0X00 0000b	R/W
000Ch		LTICR	Lite Timer Input Capture Register	00h	Read Only
000Dh	AUTO-RELOAD TIMER 2	ATCSR	Timer Control/Status Register	0X00 0000b	R/W
000Eh		CNTRH	Counter Register High	00h	Read Only
000Fh		CNTRL	Counter Register Low	00h	Read Only
0010h		ATRH	Auto-Reload Register High	00h	R/W
0011h		ATRL	Auto-Reload Register Low	00h	R/W
0012h		PWMCR	PWM Output Control Register	00h	R/W
0013h		PWM0CSR	PWM 0 Control/Status Register	00h	R/W
0014h		PWM1CSR	PWM 1 Control/Status Register	00h	R/W
0015h		PWM2CSR	PWM 2 Control/Status Register	00h	R/W
0016h		PWM3CSR	PWM 3 Control/Status Register	00h	R/W
0017h		DCR0H	PWM 0 Duty Cycle Register High	00h	R/W
0018h		DCR0L	PWM 0 Duty Cycle Register Low	00h	R/W
0019h		DCR1H	PWM 1 Duty Cycle Register High	00h	R/W
001Ah		DCR1L	PWM 1 Duty Cycle Register Low	00h	R/W
001Bh		DCR2H	PWM 2 Duty Cycle Register High	00h	R/W
001Ch		DCR2L	PWM 2 Duty Cycle Register Low	00h	R/W
001Dh		DCR3H	PWM 3 Duty Cycle Register High	00h	R/W
001Eh		DCR3L	PWM 3 Duty Cycle Register Low	00h	R/W
001Fh		ATICRH	Input Capture Register High	00h	Read Only
0020h		ATICRL	Input Capture Register Low	00h	Read Only
0021h		ATCSR2	Timer Control/Status Register 2	03h	R/W
0022h		BREAKCR	Break Control Register	00h	R/W
0023h		ATR2H	Auto-Reload Register 2 High	00h	R/W
0024h		ATR2L	Auto-Reload Register 2 Low	00h	R/W
0025h		DTGR	Dead Time Generation Register	00h	R/W
0026h		BREAKEN	Break Enable Register	03h	R/W
0027h to 002Bh	Reserved area (5 bytes)				
002Ch	Comparator Voltage Reference	VREFCR	Internal Voltage Reference Control Register	00h	R/W
002Dh	Comparator	CMPCR	Comparator and Internal Reference Control Register	00h	R/W
002Eh	WDG	WDGCR	Watchdog Control Register	7Fh	R/W

Address	Block	Register Label	Register Name	Reset Status	Remarks
0002Fh	FLASH	FCSR	Flash Control/Status Register	00h	R/W
00030h	EEPROM	EECSR	Data EEPROM Control/Status Register	00h	R/W
0031h 0032h 0033h	SPI	SPIDR SPICR SPICSR	SPI Data I/O Register SPI Control Register SPI Control Status Register	xxh 0xh 00h	R/W R/W R/W
0034h 0035h 0036h	ADC	ADCCSR ADCDRH ADCDRL	A/D Control Status Register A/D Data Register High A/D Amplifier Control/Data Low Register	00h xxh 0xh	R/W Read Only R/W
0037h	ITC	EICR	External Interrupt Control Register	00h	R/W
0038h	MCC	MCCSR	Main Clock Control/Status Register	00h	R/W
0039h 003Ah	Clock and Reset	RCCR SICSR	RC oscillator Control Register System Integrity Control/Status Register	FFh 0110 0xx0b	R/W R/W
003Bh	PLL clock select	PLLTST	PLL test register	00h	R/W
003Ch	ITC	EISR	External Interrupt Selection Register	0Ch	R/W
003Dh to 0048h	Reserved area (12 bytes)				
0049h 004Ah	AWU	AWUPR AWUCSR	AWU Prescaler Register AWU Control/Status Register	FFh 00h	R/W R/W
004Bh 004Ch 004Dh 004Eh 004Fh 0050h 0051h	DM[3]	DMCR DMSR DMBK1H DMBK1L DMBK2H DMBK2L DMCR2	DM Control Register DM Status Register DM Breakpoint Register 1 High DM Breakpoint Register 1 Low DM Breakpoint Register 2 High DM Breakpoint Register 2 Low DM Control Register 2	00h 00h 00h 00h 00h 00h 00h	R/W R/W R/W R/W R/W R/W R/W
0052h to 007Fh	Reserved area (46 bytes)				

Legend: x=undefined, R/W=read/write

Notes:

1. The contents of the I/O port DR registers are readable only in output configuration. In input configuration, the values of the I/O pins are returned instead of the DR register contents.

2. The bits associated with unavailable pins must always keep their reset value.

3. For a description of the Debug Module registers, see ICC protocol reference manual.

FLASH PROGRAM MEMORY (Cont'd)

4.4 ICC interface

ICP needs a minimum of 4 and up to 6 pins to be connected to the programming tool. These pins are:

- $\overline{\text{RESET}}$: device reset
- V_{SS}: device power supply ground
- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input serial data pin
- OSC1: main clock input for external source (not required on devices without OSC1/OSC2 pins)
- V_{DD}: application board power supply (optional, see Note 3)

Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to be implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the ICP session, the programming tool must control the $\overline{\text{RESET}}$ pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor<1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with R>1K or a reset management IC with open drain output and pull-up resistor>1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

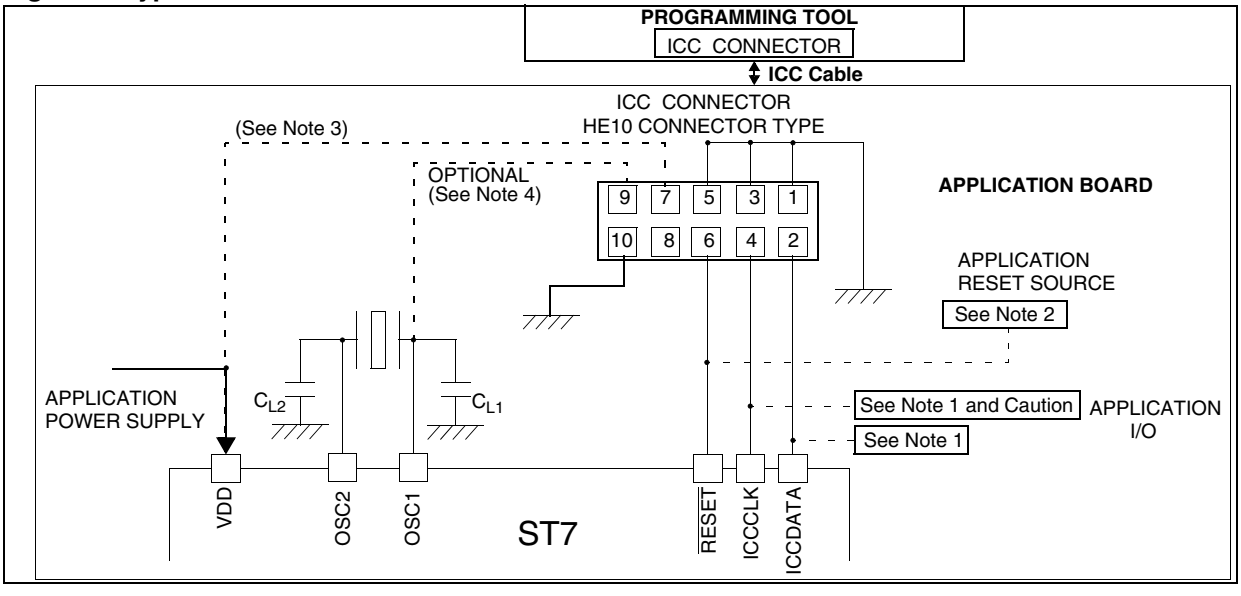
3. The use of pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multi-oscillator capability need to have OSC2 grounded in this case.

5. In 38-pulse ICC mode, the internal RC oscillator is forced as a clock source, regardless of the selection in the option byte. For ST7LITE10B devices which do not support the internal RC oscillator, the "option byte disabled" mode must be used (35-pulse ICC mode entry, clock provided by the tool).

Caution: During normal operation the ICCCLK pin must be pulled- up, internally or externally (external pull-up of 10k mandatory in noisy environment). This is to avoid entering ICC mode unexpectedly during a reset. In the application, even if the pin is configured as output, any reset will put it back in input pull-up.

Figure 6. Typical ICC Interface



CPU REGISTERS (cont'd)

CONDITION CODE REGISTER (CC)

Read/Write

Reset Value: 111x1xxx

7							0
1	1	1	H	I	N	Z	C

The 8-bit Condition Code register contains the interrupt mask and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Bit 4 = **H** *Half carry*

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instruction. It is reset by hardware during the same instructions.
0: No half carry has occurred.
1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 3 = **I** *Interrupt mask*

This bit is set by hardware when entering in interrupt or by software to disable all interrupts except the TRAP software interrupt. This bit is cleared by software.
0: Interrupts are enabled.
1: Interrupts are disabled.

This bit is controlled by the RIM, SIM and IRET instructions and is tested by the JRM and JRNM instructions.

Note: Interrupts requested while I is set are latched and can be processed when I is cleared. By default an interrupt routine is not interruptible because the I bit is set by hardware at the start of the routine and reset by the IRET instruction at the end of the routine. If the I bit is cleared by software in the interrupt routine, pending interrupts are serviced regardless of the priority level of the current interrupt routine.

Bit 2 = **N** *Negative*

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It is a copy of the 7^{th} bit of the result.
0: The result of the last operation is positive or null.
1: The result of the last operation is negative (that is, the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = **Z** *Zero*

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.
0: The result of the last operation is different from zero.
1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = **C** *Carry/borrow*

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.
0: No overflow or underflow has occurred.
1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

CPU REGISTERS (Cont'd)

STACK POINTER (SP)

Read/Write

Reset Value: 01FFh

15							8
0	0	0	0	0	0	0	1

7							0
1	SP6	SP5	SP4	SP3	SP2	SP1	SP0

The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see Figure 12).

Since the stack is 128 bytes deep, the 9 most significant bits are forced by hardware. Following an MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP6 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

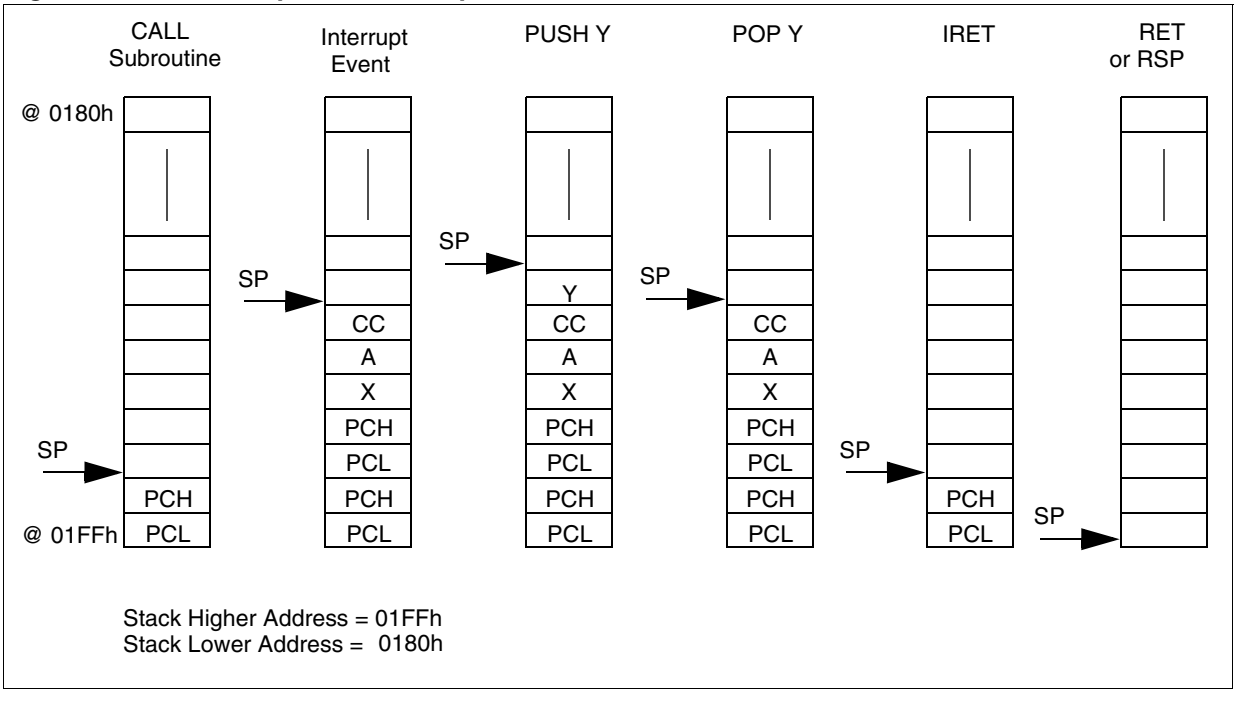
The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in Figure 12.

– When an interrupt is received, the SP is decremented and the context is pushed on the stack.

– On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 12. Stack Manipulation Example



POWER SAVING MODES (Cont'd)

9.4.1 Halt Mode Recommendations

– Make sure that an external event is available to wake up the microcontroller from Halt mode.

– When using an external interrupt to wake up the microcontroller, re-initialize the corresponding I/O as "Input Pull-up with Interrupt" before executing the HALT instruction. The main reason for this is that the I/O may be wrongly configured due to external interference or by an unforeseen logical condition.

– For the same reason, re-initialize the level sensitiveness of each external interrupt as a precautionary measure.

– The opcode for the HALT instruction is 0x8E. To avoid an unexpected HALT instruction due to a program counter failure, it is advised to clear all occurrences of the data value 0x8E from memory. For example, avoid defining a constant in program memory with the value 0x8E.

– As the HALT instruction clears the interrupt mask in the CC register to allow interrupts, the user may choose to clear all pending interrupt bits before executing the HALT instruction. This avoids entering other peripheral interrupt routines after executing the external interrupt routine corresponding to the wake-up event (reset or external interrupt).

9.5 ACTIVE-HALT MODE

ACTIVE-HALT mode is the lowest power consumption mode of the MCU with a real time clock available. It is entered by executing the 'HALT' instruction. The decision to enter either in ACTIVE-HALT or HALT mode is given by the LTCSR/ATCSR register status as shown in the following table:

LTCSR1 TB1IE bit	ATCSR OVFIE bit	ATCSR CK1 bit	ATCSR CK0 bit	Meaning
0	x	x	0	ACTIVE-HALT mode disabled
0	0	x	x	
1	x	x	x	ACTIVE-HALT mode enabled
x	1	0	1	

The MCU can exit ACTIVE-HALT mode on reception of a specific interrupt (see Table 5, "Interrupt Mapping," on page 37) or a RESET.

– When exiting ACTIVE-HALT mode by means of a RESET, a 256 or 4096 CPU cycle delay occurs. After the start up delay, the CPU resumes operation by fetching the reset vector which woke it up (see Figure 28).

– When exiting ACTIVE-HALT mode by means of an interrupt, the CPU immediately resumes operation by servicing the interrupt vector which woke it up (see Figure 28).

When entering ACTIVE-HALT mode, the I bit in the CC register is cleared to enable interrupts. Therefore, if an interrupt is pending, the MCU wakes up immediately (see Note 3).

In ACTIVE-HALT mode, only the main oscillator and the selected timer counter (LT/AT) are running to keep a wake-up time base. All other peripherals are not clocked except those which get their clock supply from another clock generator (such as external or auxiliary oscillator).

Note: As soon as ACTIVE-HALT is enabled, executing a HALT instruction while the Watchdog is active does not generate a RESET.
This means that the device cannot spend more than a defined delay in this power saving mode.

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0002h	**PAOR**	MSB							LSB
	Reset Value	0	1	0	0	0	0	0	0
0003h	**PBDR**	MSB							LSB
	Reset Value	1	1	1	1	1	1	1	1
0004h	**PBDDR**	MSB							LSB
	Reset Value	0	0	0	0	0	0	0	0
0005h	**PBOR**	MSB							LSB
	Reset Value	0	0	0	0	0	0	0	0
0006h	**PCDR**	MSB							LSB
	Reset Value	0	0	0	0	0	0	1	1
0007h	**PCDDR**	MSB							LSB
	Reset Value	0	0	0	0	0	0	0	0

10.8 MULTIPLEXED INPUT/OUTPUT PORTS

OSC1/PC0 are multiplexed on one pin (pin20) and OSC2/PC1 are multiplexed on another pin (pin 19).

11 ON-CHIP PERIPHERALS

11.1 WATCHDOG TIMER (WDG)

11.1.1 Introduction

The Watchdog timer is used to detect the occurrence of a software fault, usually generated by external interference or by unforeseen logical conditions, which causes the application program to abandon its normal sequence. The Watchdog circuit generates an MCU reset on expiry of a programmed time period, unless the program refreshes the counter's contents before the T6 bit becomes cleared.

11.1.2 Main Features

- Programmable free-running downcounter (64 increments of 16000 CPU cycles)
- Programmable reset
- Reset (if watchdog activated) when the T6 bit reaches zero
- Optional reset on HALT instruction (configurable by option byte)
- Hardware Watchdog selectable by option byte

11.1.3 Functional Description

The counter value stored in the CR register (bits T[6:0]), is decremented every 16000 machine cycles, and the length of the timeout period can be programmed by the user in 64 increments.

If the watchdog is activated (the WDGA bit is set) and when the 7-bit timer (bits T[6:0]) rolls over from 40h to 3Fh (T6 becomes cleared), it initiates a reset cycle pulling low the reset pin for typically 30µs.

Figure 34. Watchdog Block Diagram

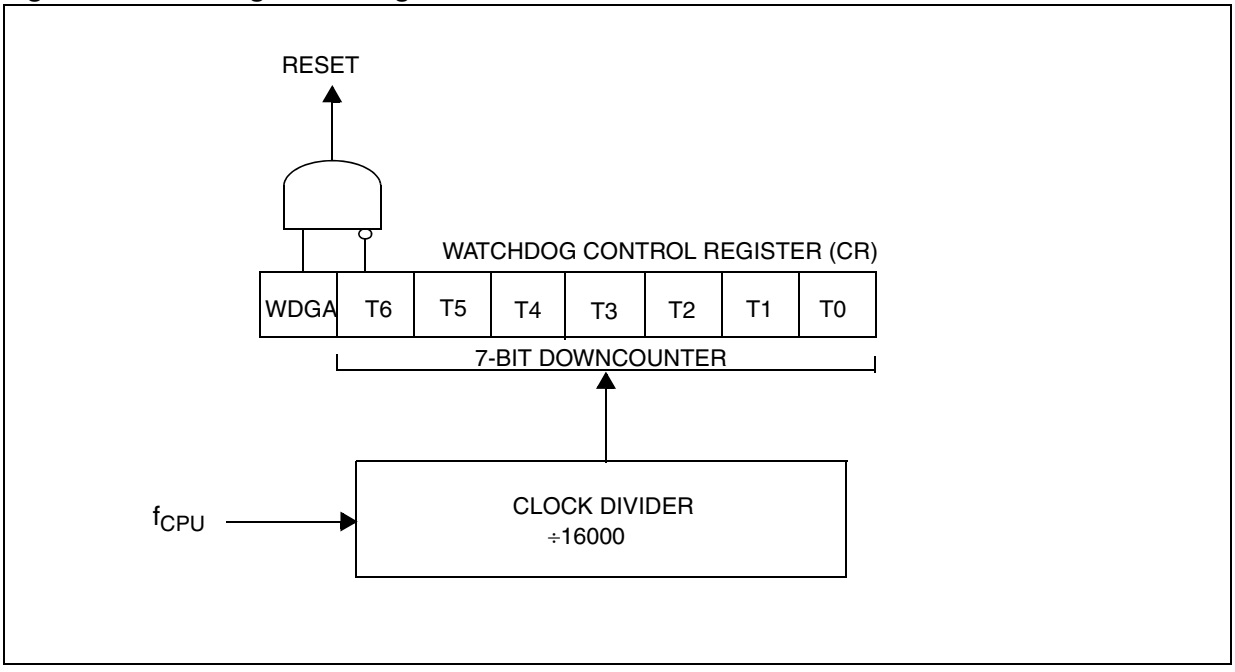
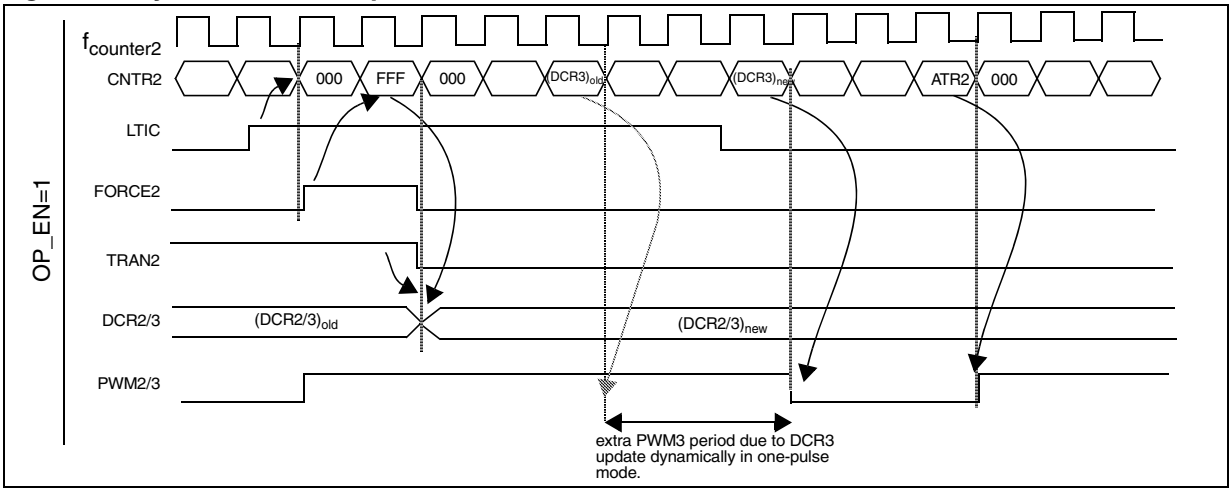


Figure 49. Dynamic DCR2/3 update in One Pulse Mode



DUAL 12-BIT AUTORELOAD TIMER 4 (Cont'd)

11.2.4 Low Power Modes

Mode	Description
WAIT	No effect on AT timer
HALT	AT timer halted.

11.2.5 Interrupts

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt	Exit from Active-Halt
Overflow Event	OVF1	OVIE1	Yes	No	Yes
AT4 IC Event	ICF	ICIE	Yes	No	No
CMP Event	CMPFx	CMPIE	Yes	No	No
Overflow Event2	OVF2	OVIE2	Yes	No	No

Note: The CMP and AT4 IC events are connected to the same interrupt vector.
The OVF event is mapped on a separate vector (see Interrupts chapter).
They generate an interrupt if the enable bit is set in the ATCSR register and the interrupt mask in the CC register is reset (RIM instruction).

LITE TIMER (Cont'd)

11.3.4 Low Power Modes

Mode	Description
SLOW	No effect on Lite timer (this peripheral is driven directly by $f_{OSC}/32$)
WAIT	No effect on Lite timer
ACTIVE HALT	No effect on Lite timer
HALT	Lite timer stops counting

11.3.5 Interrupts

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Active Halt	Exit from Halt
Timebase 1 Event	TB1F	TB1IE	Yes	Yes	No
Timebase 2 Event	TB2F	TB2IE		No	
IC Event	ICF	ICIE		No	

Note: The TBxF and ICF interrupt events are connected to separate interrupt vectors (see Interrupts chapter).

They generate an interrupt if the enable bit is set in the LTCSR1 or LTCSR2 register and the interrupt mask in the CC register is reset (RIM instruction).

11.3.6 Register Description

LITE TIMER CONTROL/STATUS REGISTER 2 (LTCSR2)
Read / Write
Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	TB2IE	TB2F

Bits 7:2 = Reserved, must be kept cleared.

Bit 1 = **TB2IE** *Timebase 2 Interrupt enable*
This bit is set and cleared by software.
0: Timebase (TB2) interrupt disabled
1: Timebase (TB2) interrupt enabled

Bit 0 = **TB2F** *Timebase 2 Interrupt Flag*
This bit is set by hardware and cleared by software reading the LTCSR register. Writing to this bit has no effect.
0: No Counter 2 overflow
1: A Counter 2 overflow has occurred

LITE TIMER AUTORELOAD REGISTER (LTARR)
Read / Write
Reset Value: 0000 0000 (00h)

7							0
AR7	AR6	AR5	AR4	AR3	AR2	AR1	AR0

Bits 7:0 = **AR[7:0]** *Counter 2 Reload Value*
These bits register is read/write by software. The LTARR value is automatically loaded into Counter 2 (LTCNTR) when an overflow occurs.

LITE TIMER COUNTER 2 (LTCNTR)
Read only
Reset Value: 0000 0000 (00h)

7							0
CNT7	CNT6	CNT5	CNT4	CNT3	CNT2	CNT1	CNT0

Bits 7:0 = **CNT[7:0]** *Counter 2 Reload Value*
This register is read by software. The LTARR value is automatically loaded into Counter 2 (LTCNTR) when an overflow occurs.

LITE TIMER CONTROL/STATUS REGISTER (LTCSR1)
Read / Write
Reset Value: 0x00 0000 (x0h)

7							0
ICIE	ICF	TB	TB1IE	TB1F	-	-	-

Bit 7 = **ICIE** *Interrupt Enable*
This bit is set and cleared by software.
0: Input Capture (IC) interrupt disabled
1: Input Capture (IC) interrupt enabled

INSTRUCTION GROUPS (cont'd)

Mnemo	Description	Function/Example	Dst	Src	H	I	N	Z	C
ADC	Add with Carry	A = A + M + C	A	M	H		N	Z	C
ADD	Addition	A = A + M	A	M	H		N	Z	C
AND	Logical And	A = A . M	A	M			N	Z	
BCP	Bit compare A, Memory	tst (A . M)	A	M			N	Z	
BRES	Bit Reset	bres Byte, #3	M						
BSET	Bit Set	bset Byte, #3	M						
BTJF	Jump if bit is false (0)	btjf Byte, #3, Jmp1	M						C
BTJT	Jump if bit is true (1)	btjt Byte, #3, Jmp1	M						C
CALL	Call subroutine								
CALLR	Call subroutine relative								
CLR	Clear		reg, M				0	1	
CP	Arithmetic Compare	tst(Reg - M)	reg	M			N	Z	C
CPL	One Complement	A = FFH-A	reg, M				N	Z	1
DEC	Decrement	dec Y	reg, M				N	Z	
HALT	Halt					0			
IRET	Interrupt routine return	Pop CC, A, X, PC			H	I	N	Z	C
INC	Increment	inc X	reg, M				N	Z	
JP	Absolute Jump	jp [TBL.w]							
JRA	Jump relative always								
JRT	Jump relative								
JRF	Never jump	jrf *							
JRIH	Jump if ext. interrupt = 1								
JRIL	Jump if ext. interrupt = 0								
JRH	Jump if H = 1	H = 1 ?							
JRNH	Jump if H = 0	H = 0 ?							
JRM	Jump if I = 1	I = 1 ?							
JRNM	Jump if I = 0	I = 0 ?							
JRMI	Jump if N = 1 (minus)	N = 1 ?							
JRPL	Jump if N = 0 (plus)	N = 0 ?							
JREQ	Jump if Z = 1 (equal)	Z = 1 ?							
JRNE	Jump if Z = 0 (not equal)	Z = 0 ?							
JRC	Jump if C = 1	C = 1 ?							
JRNC	Jump if C = 0	C = 0 ?							
JRULT	Jump if C = 1	Unsigned <							
JRUGE	Jump if C = 0	Jmp if unsigned >=							
JRUGT	Jump if (C + Z = 0)	Unsigned >							

13 ELECTRICAL CHARACTERISTICS

13.1 PARAMETER CONDITIONS

Unless otherwise specified, all voltages are referred to V_{SS}.

13.1.1 Minimum and Maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A=25°C and T_A=$T_A$max (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3Σ).

13.1.2 Typical values

Unless otherwise specified, typical data are based on T_A=25°C, V_{DD}=5V (for the 4.5V≤V_{DD}≤5.5V voltage range) and V_{DD}=3.3V (for the 3V≤V_{DD}≤3.6V voltage range). They are given only as design guidelines and are not tested.

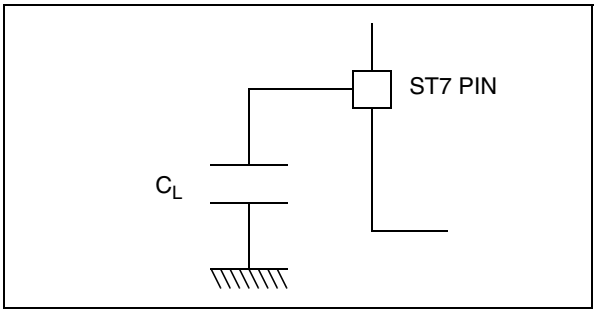
13.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

13.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in Figure 63.

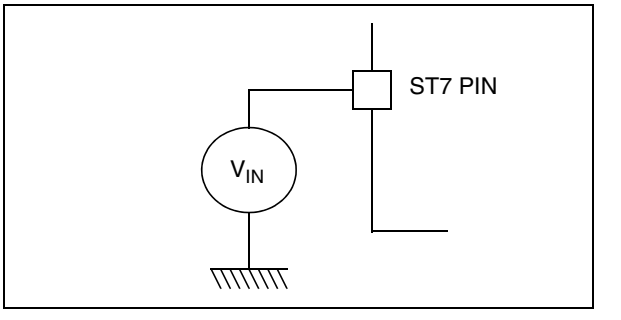
Figure 63. Pin loading conditions



13.1.5 Pin input voltage

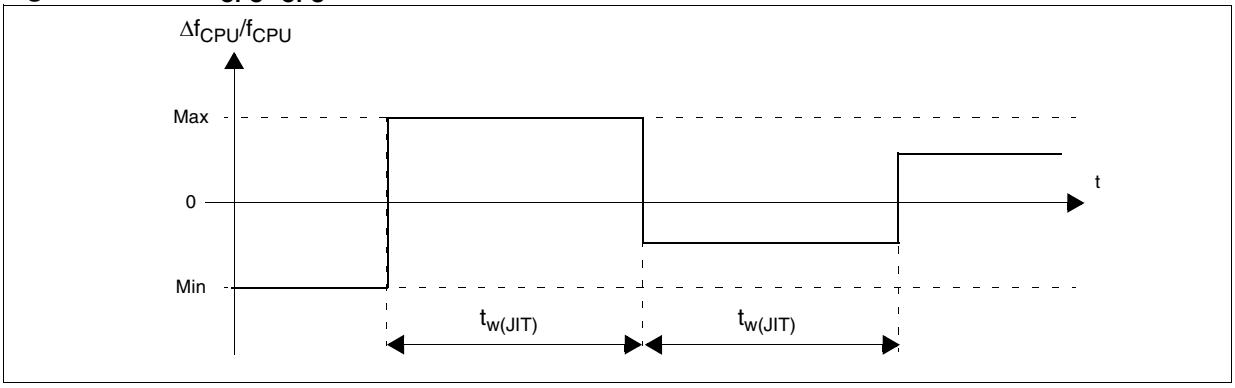
The input voltage measurement on a pin of the device is described in Figure 64.

Figure 64. Pin input voltage



OPERATING CONDITIONS (Cont'd)

Figure 70. PLL $\Delta f_{CPU}/f_{CPU}$ versus time



13.3.5.3 32MHz PLL

T_A = -40 to 125°C, unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit
V_{DD}	Voltage [1]	4.5	5	5.5	V
f_{PLL32}	Frequency [1]		32		MHz
f_{INPUT}	Input Frequency	7	8	9	MHz

Note:
1. 32 MHz is guaranteed within this voltage range.

CLOCK AND TIMING CHARACTERISTICS (Cont'd)

13.5.4 Crystal and Ceramic Resonator Oscillators

The ST7 internal clock can be supplied with ten different Crystal/Ceramic resonator oscillators. All the information given in this paragraph are based on characterization results with specified typical external components. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. Refer to the crystal/ceramic resonator manufacturer for more details (frequency, package, accuracy...).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{CrOSC}	Crystal Oscillator Frequency		2		16	MHz
C_{L1} C_{L2}	Recommended load capacitance versus equivalent serial resistance of the crystal or ceramic resonator (R_S)		See table below			pF

Supplier	f_{CrOSC} (MHz)	Typical Ceramic Resonators[1]		CL1 [3] [pF]	CL2 [3] [pF]	Rd [Ω]	Supply Voltage Range [V]	Temperature Range [°C]
		Type[2]	Reference					
Murata	1	SMD	CSBFB1M00J58-R0	220	*220*	2.2k	3.3V to 5.5V	-40 to 85
		LEAD	CSBLA1M00J58-B0	220	220	2.2k		
	2	SMD	CSTCC2M00G56Z-R0	(47)	(47)	0	3.0V to 5.5V	
	4	SMD	CSTCR4M00G53Z-R0	(15)	(15)	0		
		LEAD	CSTLS4M00G53Z-B0	(15)	(15)	0		
	8	SMD	CSTCE8M00G52Z-R0	(10)	(10)	0		
		LEAD	CSTLS8M00G53Z-B0	(15)	(15)	0		
	12	SMD	CSTCE12M0G52Z-R0	(10)	(10)	0	3.3V to 5.5V	
	16	SMD	CSTCE16M0V51Z-R0	(5)	(5)	0		
		LEAD	CSTLS16M0X51Z-B0	(5)	(5)	0		

Notes:

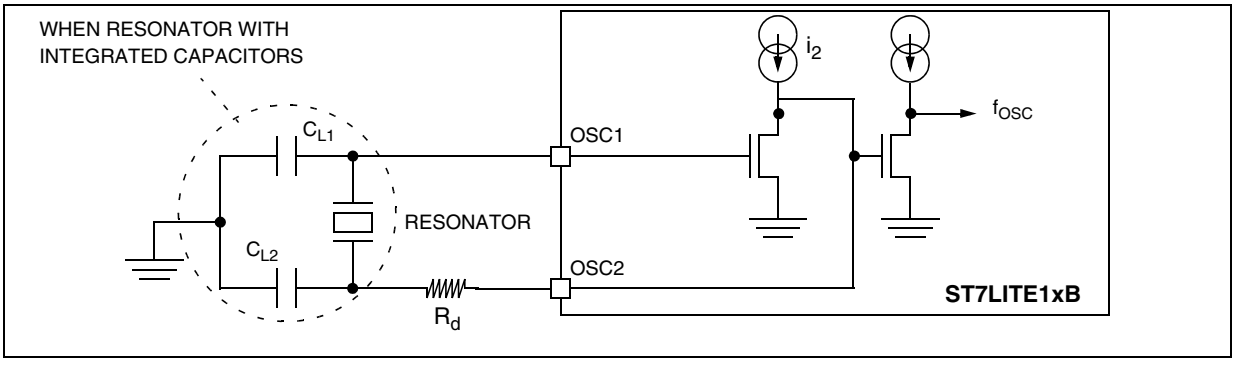
1. Resonator characteristics given by the ceramic resonator manufacturer. For more information on these resonators, please consult www.murata.com

2. SMD = [-R0: Plastic tape package (∅ =180mm)]

LEAD = [-B0: Bulk]

3. () means load capacitor built in resonator

Figure 79. Typical Application with a Crystal or Ceramic Resonator



I/O PORT PIN CHARACTERISTICS (Cont'd)

Figure 81. Typical V_{OL} at V_{DD}=2.7V (standard)

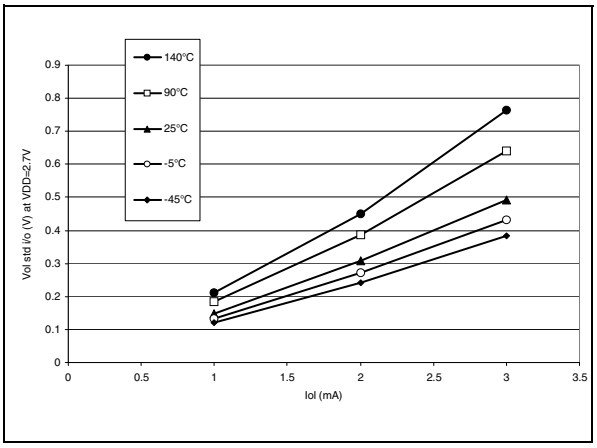


Figure 82. Typical V_{OL} at V_{DD}=3.3V (standard)

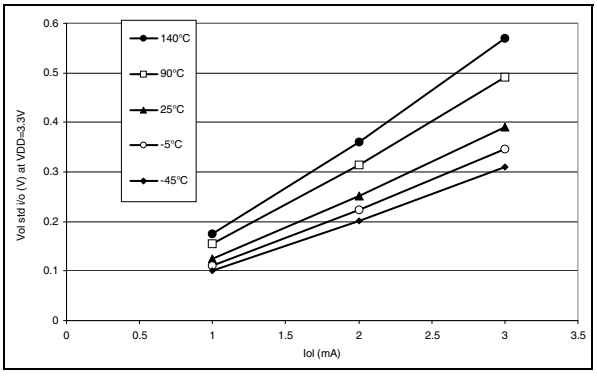


Figure 83. Typical V_{OL} at V_{DD}=5V (standard)

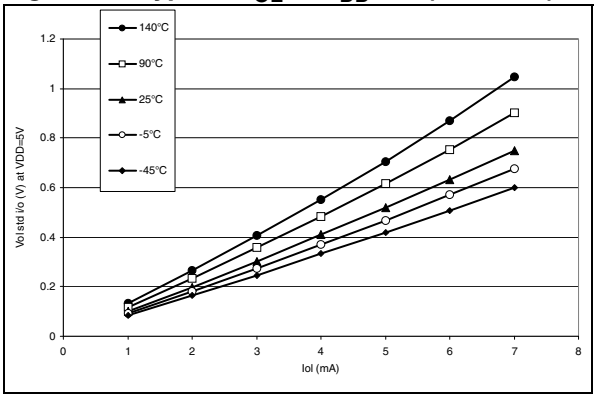


Figure 84. Typical V_{OL} at V_{DD}=2.7V (Port C)

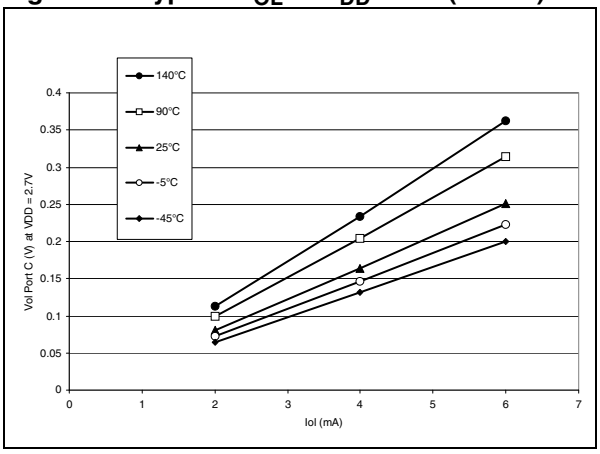


Figure 85. Typical V_{OL} at V_{DD}=3.3V (Port C)

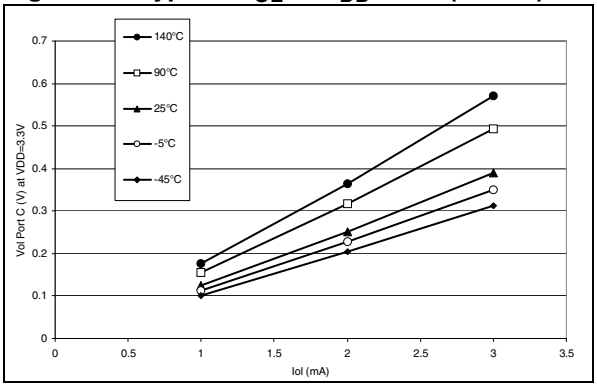
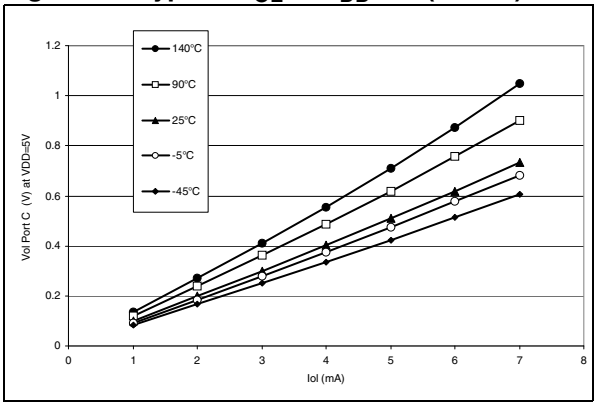


Figure 86. Typical V_{OL} at V_{DD}=5V (Port C)



13.9 CONTROL PIN CHARACTERISTICS

13.9.1 Asynchronous $\overline{\text{RESET}}$ Pin

T_A = -40°C to 125°C, unless otherwise specified

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IL}	Input low level voltage [1]			V_{ss} - 0.3		0.3xV_{DD}	V
V_{IH}	Input high level voltage [1]			0.7xV_{DD}		V_{DD} + 0.3	
V_{hys}	Schmitt trigger voltage hysteresis [1]				2		V
V_{OL}	Output low level voltage [1][2]	V_{DD}=5V	I_{IO}=+5mA $T_A \leq 85°C$		0.5	1.0	V
			I_{IO}=+2mA $T_A \leq 85°C$		0.2	0.4	
R_{ON}	Pull-up equivalent resistor [3]	V_{DD}=5V		20	40	80	kΩ
		V_{DD}=3V [1]		40	70	120	
$t_{w(RSTL)out}$	Generated reset pulse duration	Internal reset sources			30		µs
$t_{h(RSTL)in}$	External reset pulse hold time [4]			20			µs
$t_{g(RSTL)in}$	Filtered glitch duration				200		ns

Notes:

1. Data based on characterization results, not tested in production.

2. The I_{IO} current sunk must always respect the absolute maximum rating specified in Section 13.2.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS}.

3. The R_{ON} pull-up equivalent resistor is based on a resistive transistor. Specified for voltages on $\overline{\text{RESET}}$ pin between V_{ILmax} and V_{DD}

4. To guarantee the reset of the device, a minimum pulse has to be applied to the $\overline{\text{RESET}}$ pin. All short pulses applied on $\overline{\text{RESET}}$ pin with a duration below $t_{h(RSTL)in}$ can be ignored.

14.2 SOLDERING INFORMATION

In accordance with the RoHS European directive, all STMicroelectronics packages have been converted to lead-free technology, named ECOPACK™.

- ECOPACK™ packages are qualified according to the JEDEC STD-020C compliant soldering profile.
- Detailed information on the STMicroelectronics ECOPACK™ transition program is available on www.st.com/stonline/leadfree/, with specific technical Application notes covering the main technical aspects related to lead-free conversion (AN2033, AN2034, AN2035, AN2036).

Backward and forward compatibility:

The main difference between Pb and Pb-free soldering process is the temperature range.

– ECOPACK™ TQFP, SDIP, SO and QFN20 packages are fully compatible with Lead (Pb) containing soldering process (see application note AN2034)

– TQFP, SDIP and SO Pb-packages are compatible with Lead-free soldering process, nevertheless it's the customer's duty to verify that the Pb-packages maximum temperature (mentioned on the Inner box label) is compatible with their Lead-free soldering temperature.

Table 25. Soldering Compatibility (wave and reflow soldering process)

Package	Plating material devices	Pb solder paste	Pb-free solder paste
SDIP & PDIP	Sn (pure Tin)	Yes	Yes *
QFN	Sn (pure Tin)	Yes	Yes *
TQFP and SO	NiPdAu (Nickel-palladium-Gold)	Yes	Yes *

* Assemblers must verify that the Pb-package maximum temperature (mentioned on the Inner box label) is compatible with their Lead-free soldering process.

Table 29. ST7 Application Notes

IDENTIFICATION	DESCRIPTION
AN1039	ST7 MATH UTILITY ROUTINES
AN1064	WRITING OPTIMIZED HIWARE C LANGUAGE FOR ST7
AN1071	HALF DUPLEX USB-TO-SERIAL BRIDGE USING THE ST72611 USB MICROCONTROLLER
AN1106	TRANSLATING ASSEMBLY CODE FROM HC05 TO ST7
AN1179	PROGRAMMING ST7 FLASH MICROCONTROLLERS IN REMOTE ISP MODE (IN-SITU PROGRAMMING)
AN1446	USING THE ST72521 EMULATOR TO DEBUG A ST72324 TARGET APPLICATION
AN1477	EMULATED DATA EEPROM WITH XFLASH MEMORY
AN1478	PORTING AN ST7 PANTA PROJECT TO CODEWARRIOR IDE
AN1527	DEVELOPING A USB SMARTCARD READER WITH ST7SCR
AN1575	ON-BOARD PROGRAMMING METHODS FOR XFLASH AND HDFLASH ST7 MCUS
AN1576	IN-APPLICATION PROGRAMMING (IAP) DRIVERS FOR ST7 HDFLASH OR XFLASH MCUS
AN1577	DEVICE FIRMWARE UPGRADE (DFU) IMPLEMENTATION FOR ST7 USB APPLICATIONS
AN1601	SOFTWARE IMPLEMENTATION FOR ST7DALI-EVAL
AN1603	USING THE ST7 USB DEVICE FIRMWARE UPGRADE DEVELOPMENT KIT (DFU-DK)
AN1635	ST7 CUSTOMER ROM CODE RELEASE INFORMATION
AN1754	DATA LOGGING PROGRAM FOR TESTING ST7 APPLICATIONS VIA ICC
AN1796	FIELD UPDATES FOR FLASH BASED ST7 APPLICATIONS USING A PC COMM PORT
AN1900	HARDWARE IMPLEMENTATION FOR ST7DALI-EVAL
AN1904	ST7MC THREE-PHASE AC INDUCTION MOTOR CONTROL SOFTWARE LIBRARY
AN1905	ST7MC THREE-PHASE BLDC MOTOR CONTROL SOFTWARE LIBRARY
SYSTEM OPTIMIZATION	
AN1711	SOFTWARE TECHNIQUES FOR COMPENSATING ST7 ADC ERRORS
AN1827	IMPLEMENTATION OF SIGMA-DELTA ADC WITH ST7FLITE05/09
AN2009	PWM MANAGEMENT FOR 3-PHASE BLDC MOTOR DRIVES USING THE ST7FMC
AN2030	BACK EMF DETECTION DURING PWM ON TIME BY ST7MC

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